



Final Product Change Notification

202604001F01 : MCXN23x 184VFBGA Assembly and Final Test Manufacturing Site Expansion from NXP-ATTJ to NXP-ATKL

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 25, 2026 **Effective Date:** Sep 23, 2026

Dear Emma Tempest,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Management summary

NXP Semiconductors announces the Assembly and Test site expansion for the MCXN23x VFBGA184 associated with this notification, from the current NXP-ATTJ, Tianjin, China Manufacturing site to the NXP-ATKL, Kuala Lumpur, Malaysia Manufacturing site.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☒ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☐ Wafer Fab Location	☒ Assembly Location	☒ Packing/Shipping/Labeling	☒ Test Location	☐ Electrical spec./Test coverage
☐ Firmware ☐ Other				

Notification Overview

Description

NXP Semiconductors announces the Assembly and Test site expansion for the MCXN23x VFBGA184 associated with this notification, from the current NXP-ATTJ, Tianjin, China Manufacturing site to the NXP-ATKL, Kuala Lumpur, Malaysia Manufacturing site.

Manufacturing site expansion was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

Qualification of NXP-ATKL, Kuala Lumpur, Malaysia is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

Trace code for additional assembly site, "Q", is laser marked on the product package marking on line 2

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jun 30, 2026

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Since this is Manufacturing site expansion, customers could receive product from either manufacturing site.

Additional information

Self qualification:[view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 25, 2026.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management,

Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New 12NC	New Orderable Part Number	New Product Type	New Product Description	Product Line	Notes	STG	Mask Set	Quality Segment
935463512518	MCXN236VDFR	MCXN236VDFR	MCXN11, 184BGA	(V)FBGA184M	SOT2172-1	RFS	No					BLM1				D (Non Automotive Special)
935463512557	MCXN236VDFT	MCXN236VDFT	MCXN11, 184BGA	(V)FBGA184M	SOT2172-1	RFS	No					BLM1				D (Non Automotive Special)
935463513518	MCXN235VDFR	MCXN235VDFR	MCXN11, 184BGA	(V)FBGA184M	SOT2172-1	RFS	No					BLM1				D (Non Automotive Special)
935463513557	MCXN235VDFT	MCXN235VDFT	MCXN11, 184BGA	(V)FBGA184M	SOT2172-1	RFS	No					BLM1				D (Non Automotive Special)